New Product



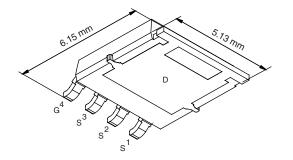
SiJ400DP

Vishay Siliconix

N-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A) ^{a, g}	Q _g (Typ.)		
30	0.004 at V _{GS} = 10 V	32	45 nC		
	0.005 at V _{GS} = 4.5 V	32	43110		



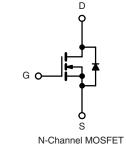


FEATURES

- Halogen-free According to IEC 61249-2-21 . Definition
- TrenchFET[®] Power MOSFET
- 100 % Rg Tested
- 100 % UIS Tested
- Compliant to RoHS Directive 2002/95/EC

APPLICATIONS

- POL
- VRM
- DC/DC



Ordering Information: SiJ400DP-T1-GE3 (Lead (Pb)-free and Halogen-free)

Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	30	V	
Gate-Source Voltage		V _{GS}	± 20		
Continuous Drain Current ($T_1 = 150 \text{ °C}$)	T _C = 25 °C T _C = 70 °C	I _D	32 ^g 32 ^g	_	
	T _A = 25 °C T _A = 70 °C		26.3 ^{b, c} 21 ^{b, c}	A	
Pulsed Drain Current		I _{DM}	80		
Continuous Source-Drain Diode Current	T _C = 25 °C T _A = 25 °C	I _S	32 ^g 4.5 ^{b, c}		
Single Pulse Avalanche Current		I _{AS}	40		
Single Pulse Avalanche Energy L = 0.1 mH		E _{AS}	80	mJ	
	T _C = 25 °C		69.4		
Maximum Power Dissipation	T _C = 70 °C	P _D	44.4	w	
Maximum Power Dissipation	T _A = 25 °C	U'U	5.0 ^{b, c}	~ ~ ~	
	T _A = 70 °C		3.2 ^{b, c}		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150		
Soldering Recommendations (Peak Temperature) ^{d, e}			260		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{b, f}	t ≤ 10 s	R _{thJA}	20	25	°C/W	
Maximum Junction-to-Case (Drain)	Steady State	R _{thJC}	1.3	1.8		

Notes:

a. Based on T_C = 25 °C.

b. Surface Mounted on 1" x 1" FR4 board.

c. t = 10 s.

d. See Solder Profile (www.vishay.com/ppg?73257). The PowerPAK SO-8L is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.

e. Rework Conditions: manual soldering with a soldering iron is not recommended for leadless components.

f. Maximum under Steady State conditions is 65 °C/W.

g. Package limited.



RoHS COMPLIANT HALOGEN FREE

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static	-						
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 V, I_{D} = 250 \mu A$	30			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = 250 μA		28		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	$I_D = 250 \ \mu A$		- 6.2			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \ \mu A$	1.2		2.5	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 30 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			1	μΑ	
		$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$			10		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5$ V, $V_{GS} = 10$ V	30			Α	
Drain-Source On-State Resistance ^a	_	V _{GS} = 10 V, I _D = 20 A		0.0033	0.004		
	R _{DS(on)}	V _{GS} = 4.5 V, I _D = 10 A		0.0041	0.005	Ω	
Forward Transconductance ^a	9 _{fs}	V _{DS} = 10 V, I _D = 20 A		90		S	
Dynamic ^b							
Input Capacitance	C _{iss}			7765		pF	
Output Capacitance	C _{oss}	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, \text{ f} = 1 \text{ MHz}$		930			
Reverse Transfer Capacitance	C _{rss}			437			
Total Gate Charge	Q _g	$V_{DS} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 20 \text{ A}$		100	150	nC	
				45	70		
Gate-Source Charge	Q _{gs}	V_{DS} = 15 V, V_{GS} = 4.5 V, I_D = 20 A		18.6			
Gate-Drain Charge	Q _{gd}			9.1			
Gate Resistance	Rg	f = 1 MHz	0.3	0.85	1.7	Ω	
Turn-On Delay Time	t _{d(on)}			16	30	- ns	
Rise Time	t _r	V_{DD} = 15 V, R_L = 1.5 Ω		10	20		
Turn-Off Delay Time	t _{d(off)}	$\text{I}_\text{D} \cong$ 10 A, V_GEN = 10 V, R_g = 1 Ω		42	80		
Fall Time	t _f			8	16		
Turn-On Delay Time	t _{d(on)}			48	90		
Rise Time	t _r	V_{DD} = 15 V, R_L = 1.5 Ω		66	120		
Turn-Off Delay Time	t _{d(off)}	$\text{I}_\text{D} \cong$ 10 A, V_GEN = 4.5 V, R_g = 1 Ω		49	90		
Fall Time	t _f			20	40		
Drain-Source Body Diode Characteristic	cs			•	1		
Continuous Source-Drain Diode Current	ا _S	$T_{C} = 25 \ ^{\circ}C$			32	۸	
Pulse Diode Forward Current ^a	I _{SM}				80	A	
Body Diode Voltage	V _{SD}	I _S = 3 A		0.73	1.1	V	
Body Diode Reverse Recovery Time	t _{rr}			43	80	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	I _F = 10 A, dl/dt = 100 A/μs, T _{.1} = 25 °C		48	88	nC	
Reverse Recovery Fall Time	t _a	$r_F = 10 \text{ A}, \text{ u/u} = 100 \text{ A/} \mu \text{s}, r_J = 25 \text{ °C}$		22			
Reverse Recovery Rise Time				21		ns	

Notes:

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



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T_C = - 55 °C

Ciss

4

5

3

18

 $V_{GS} = 10 V$

24

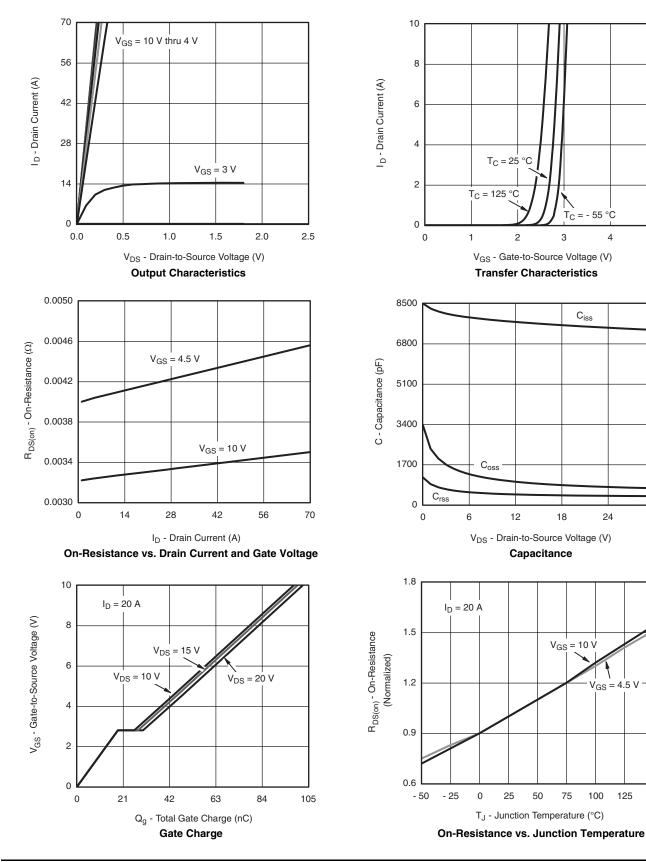
V_{GS} = 4.5 V

100

75

30

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



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150

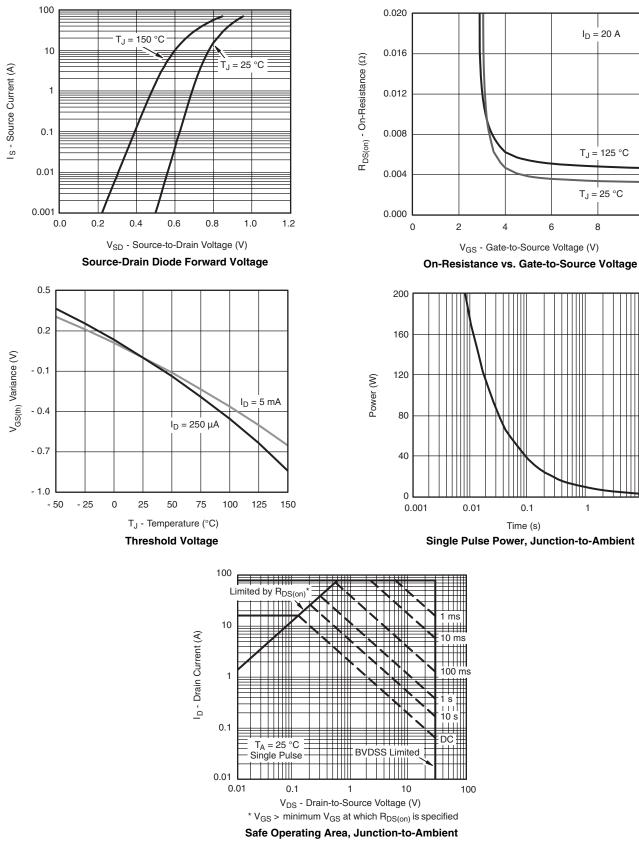
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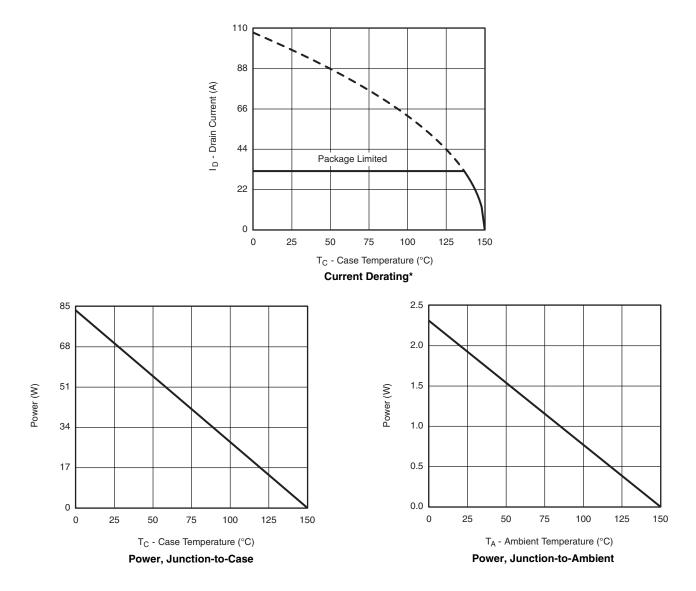
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





SiJ400DP Vishay Siliconix

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

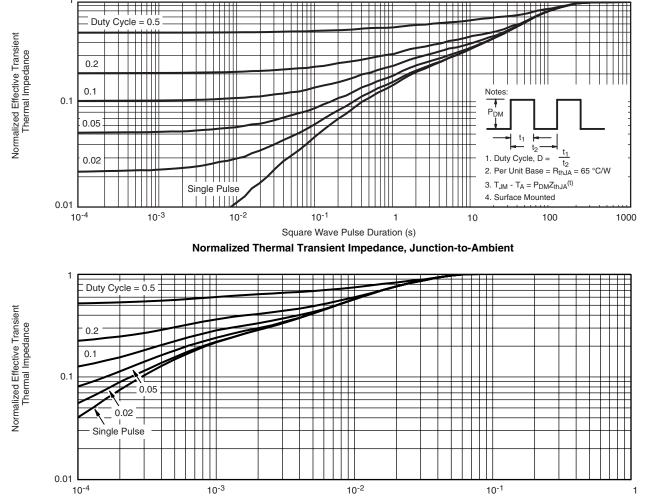


* The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Square Wave Pulse Duration (s)

Normalized Thermal Transient Impedance, Junction-to-Case

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see <u>www.vishay.com/ppg?64986</u>.



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